



Material Content Data Sheet



Sales Product Name		BGS 13GA14 E6327		Issued		20. July 2018			
MA#		MA001362838							
Package		PG-ATSLP-14-4		Weight*		5.34 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.218	4.08	4.08	40772	40772	
bumps	non noble metal	copper	7440-50-8	0.024	0.45	0.45	4462	4462	
encapsulation	organic material	carbon black	1333-86-4	0.019	0.35		3494		
	plastics	epoxy resin	-	0.541	10.13		101330		
leadfinish	inorganic material	silicondioxide	60676-86-0	3.173	59.39	69.87	593998	698822	
	noble metal	gold	7440-57-5	0.078	1.47		14693		
substrate	non noble metal	nickel	7440-02-0	0.090	1.68	3.15	16757	31450	
	organic material	carbon black	1333-86-4	0.002	0.03		312		
ubm	plastics	epoxy resin	-	0.065	1.22		12167		
	inorganic material	silicondioxide	60676-86-0	0.489	9.15		91514		
solder	non noble metal	copper	7440-50-8	0.509	9.52	19.92	95207	199200	
	non noble metal	copper	7440-50-8	0.001	0.02		152		
solder resists	non noble metal	titanium	7440-32-6	0.000	0.01		54		
	non noble metal	tungsten	7440-33-7	0.000	0.00	0.03	28	234	
*deviation	noble metal	silver	7440-22-4	0.000	0.00		38		
	non noble metal	tin	7440-31-5	0.009	0.16	0.16	1599	1637	
*deviation	inorganic material	bariumsulfate	7727-43-7	0.027	0.50		5036		
	inorganic material	silicondioxide	60676-86-0	0.027	0.50		4977		
		plastics	acrylic resin	-	0.072	1.34	2.34	13410	23423
						Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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